

**SMBYW02-200**

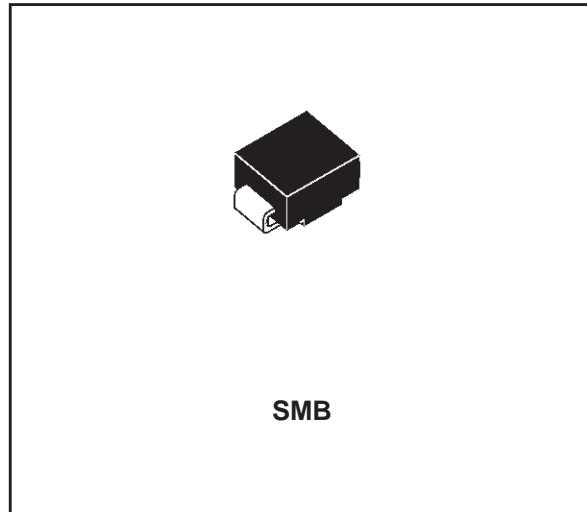
HIGH EFFICIENCY FAST RECOVERY RECTIFIER DIODES

FEATURES

- SUITED FOR SMPS
- VERY LOW FORWARD LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- HIGH SURGE CURRENT CAPABILITY
- HIGH AVALANCHE ENERGY CAPABILITY
- SURFACE MOUNT DEVICE

DESCRIPTION

Single chip rectifier suited for Switch Mode Power Supply and high frequency DC to DC converters. Packaged in SMB, this surface mount device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
$I_{F(RMS)}$	RMS forward current		10	A
$I_{F(AV)}$	Average forward current	$T_J=100^\circ\text{C}$ $\delta = 0.5$	2	A
I_{FSM}	Non repetitive surge peak forward current	$t_p=10\text{ms}$ sinusoidal	50	A
T_{stg} T_J	Storage and junction temperature range		- 40 to + 150 - 40 to + 150	°C °C

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		200	V

THERMAL RESISTANCE

Symbol	Parameter		Value	Unit
$R_{th}(j-l)$	Junction-leads		25	°C/W

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ELECTRICAL CHARACTERISTICS STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
V_F *	$T_j = 25^\circ C$	$I_F = 6 A$			1.25	V
	$T_j = 100^\circ C$	$I_F = 2 A$		0.8	0.85	
I_R **	$T_j = 25^\circ C$	$V_R = V_{RRM}$			10	μA
	$T_j = 100^\circ C$			0.1	0.3	mA

Pulse test : * $t_p = 380 \mu s$, duty cycle < 2 %

** $t_p = 5 ms$, duty cycle < 2 %

RECOVERY CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
t_{rr}	$T_j = 25^\circ C$	$I_F = 1A$ $V_R = 30V$		26	35	ns
t_{fr}	$T_j = 25^\circ C$	$I_F = 1A$ $V_{FR} = 1.1 \times V_F$		30		ns
V_{FP}	$T_j = 25^\circ C$	$I_F = 1A$	$tr = 10 ns$	5		V

To evaluate the conduction losses use the following equation:

$$P = 0.7 \times I_{F(AV)} + 0.075 \times I_F^2(RMS)$$

Voltage (V)	200
Marking	A20

Laser marking
Logo indicates cathode

Fig.1 : Low frequency power losses versus average current.

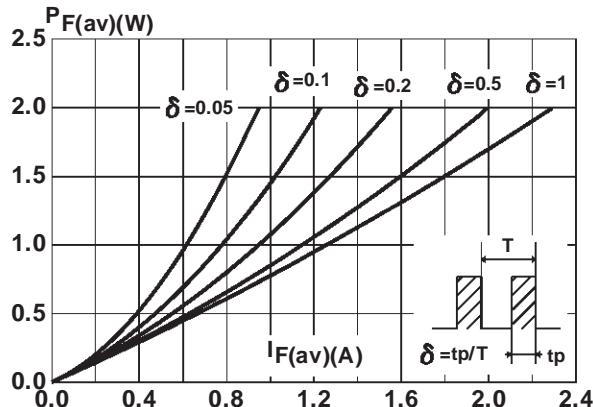


Fig.3 : Non repetitive surge peak forward current versus overload duration.

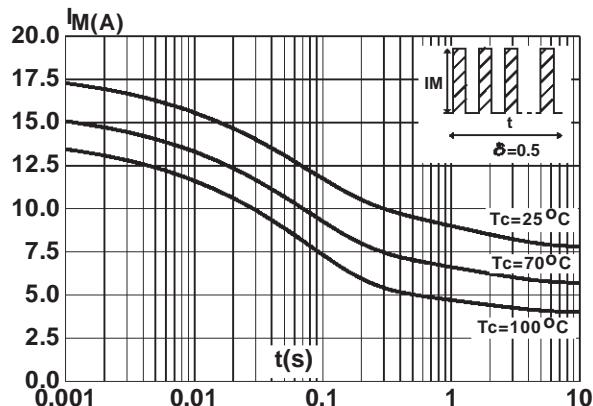


Fig.5 : Voltage drop versus forward current. (Maximum values)

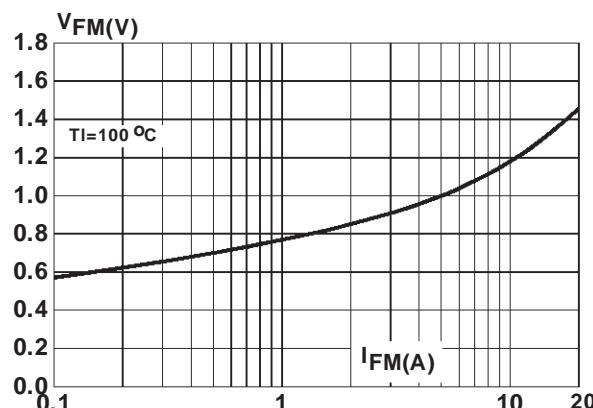


Fig.2 : Peak current versus form factor.

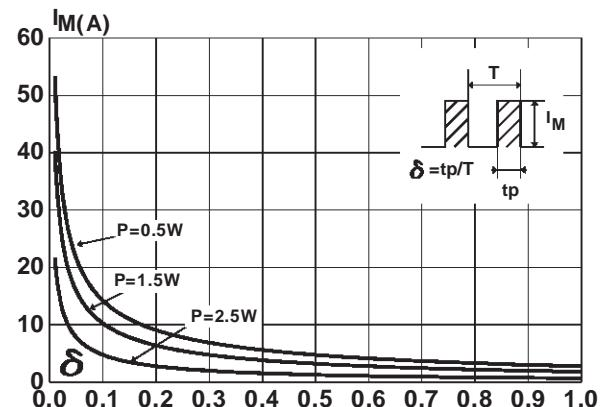


Fig.4 : Relative variation of thermal impedance junction to lead versus pulse duration.

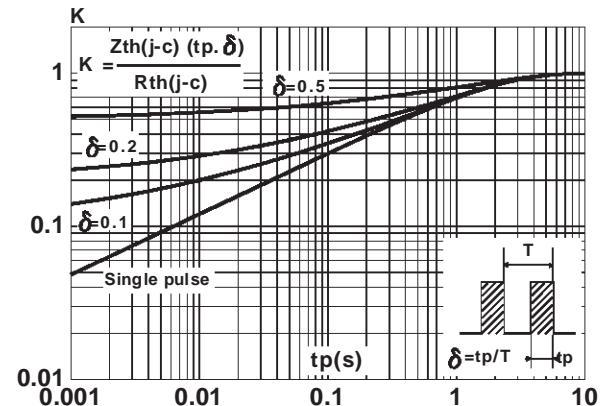
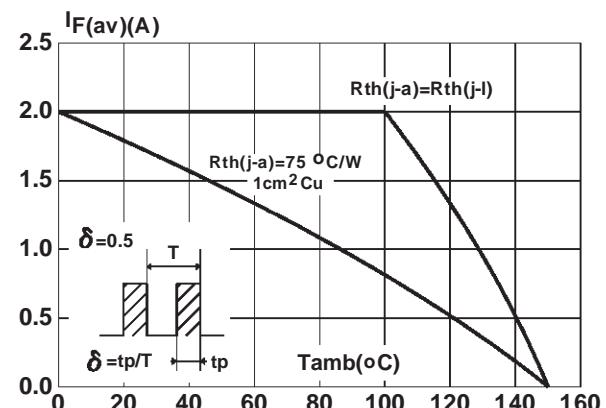


Fig.6 : Average current versus ambient temperature. (duty cycle : 0.5)



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Fig.7 : Capacitance versus reverse voltage applied.

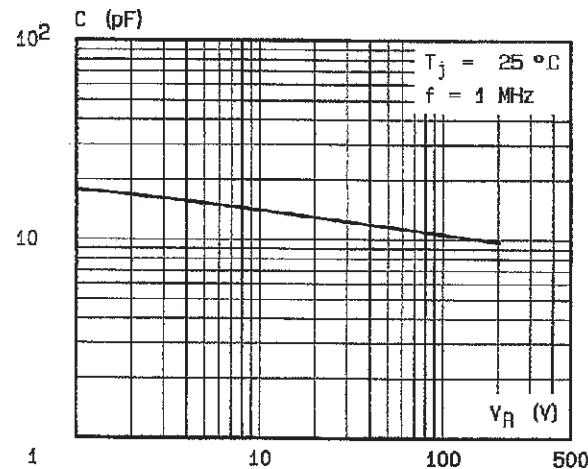


Fig.9 : Peak reverse current versus dI_F/dt.

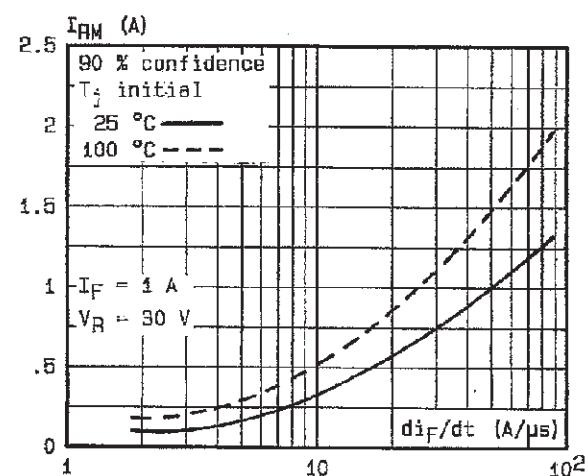


Fig.11 : Thermal resistance junction to ambient versus copper surface under each lead.

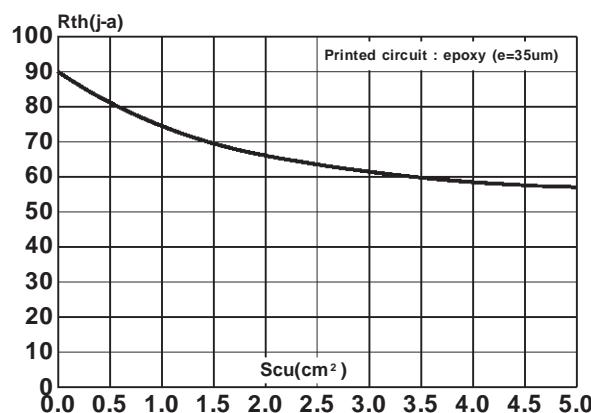


Fig.8 : Recovery time versus dI_F/dt.

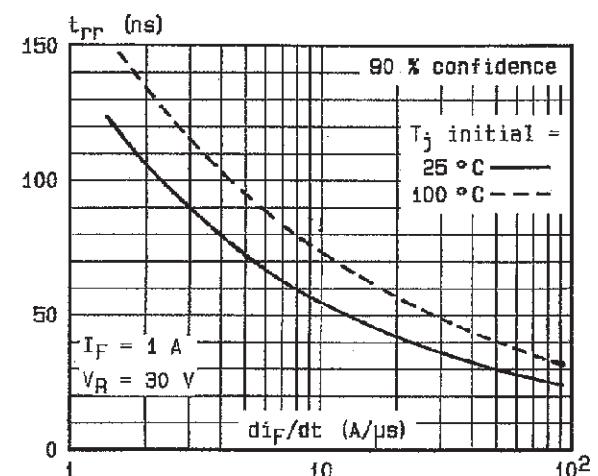
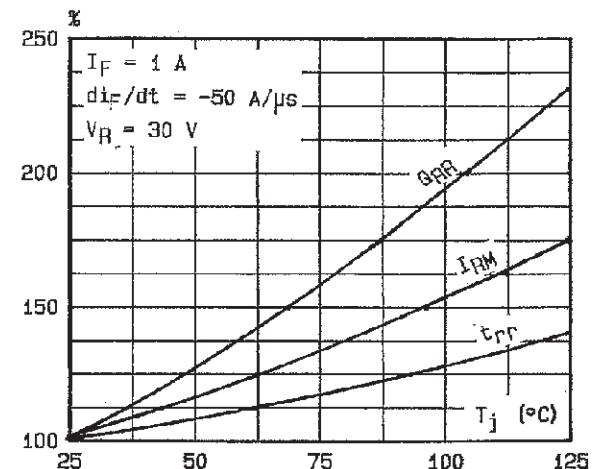


Fig.10 : Dynamic parameters versus junction temperature.



PACKAGE MECHANICAL DATA

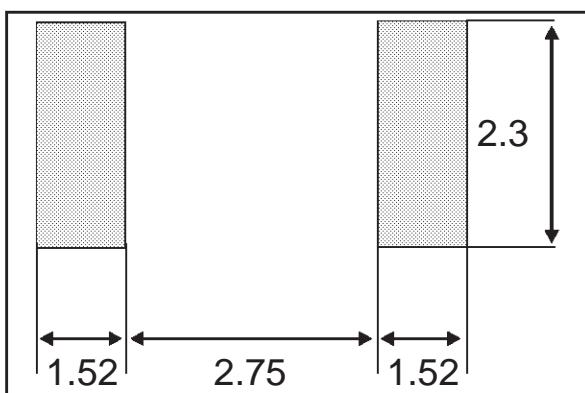
SMB

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
A3	0.05	0.30	0.002	0.012
b	1.95	2.20	0.077	0.087
C	0.15	0.41	0.006	0.016
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
E	5.10	5.60	0.201	0.220
L	0.75	1.60	0.030	0.063
R1	0.15		0.006	
R2	0.15		0.006	

FOOTPRINT DIMENSIONS (in millimeters)

SMB

- Weight : 0.12 g.
- Laser marking
- Logo indicates cathode



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